



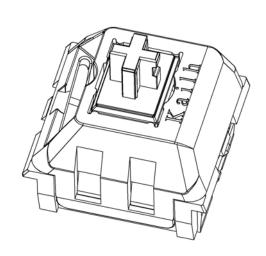


Document Number:

KH-PS1801-02

产品规格书

Product Specification



<u>P/N:</u>			Title:		
	CPG15	1101D234	PG15	11 Keyboard	Switch
Rev.	ECN	Release and Revision Description:	Prepared By /Date:	Checked By/Date:	Approved By/Date:
A		New releasing 初版发行	易金平 2018-1-2	胡远锋 2018-1-2	David 2018-1-2



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1. Scope/范围:

This Product Specification covers the requirement of Mechanical Keyboard switch on product performance, test methods and quality assurance provisions.

本规格书内容涵盖机械键盘开关产品的要求,包括性能指标、测试方法及质量保证方面等。

2. Product Application/产品应用:

Mainly applied on computer keyboards, cash registers, industrial equipment and Man-Machine interface.

主要适用于电脑键盘, 收银机、工业设备和人机界面。

3. Technology

Parameters/技术参数

Ambient Humidity 工作湿度: 45~85% R.H.; Operating Temperature Range 使用温度范围: -10° ~+ 70° ; Storage Temperature Range 保存温度范围: -20° ~+ 70° ;

Suggested storage period 贮存期限: about 6 months 最多 6 个月

Require the tin part on the switch terminals should keep good after storage guarantee date 要求贮存期后开关端子部分上锡仍然良好。

Normal Condition:

Ambient temperature 环境温度: 20±2℃

Relative humidity 相对湿度: 65%±5% R.H.; Air pressure 气压: 86~101KPa;

4. Ratings/额定性能要求

Rating 额定负荷:

Insulation Resistance 绝缘电阻: Withstand Voltage 耐电压:

Mechanical Life 机械寿命:

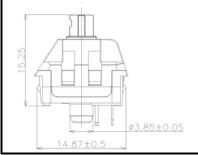
10mA AC/DC max.10 μ A DC min; ≥100M Ω/DC 500V; 100V AC 1 Minute:

12V AC/DC max.2V DC min.

50,000,000 Cycles (Without load).

5. Profile Dimensions /外形尺寸









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6. Electrical Performance/电气性能

Item 项目	Description 项目描述	Test Condition 测试条件	Requirement 规格要求
6.1	Static load: (Operation force)x2, which is applied on the center of Switch stem. 静态负载:动作力的 2 倍,施加在手柄中心. Contact Resistance 接触电阻 Measurement tool: Contact resistance Meter. 测量工具:微电流接触电阻计(1KHz, 20mV,5~50mA) 在低电流(≤100mA)条件下测试. Measured at low current (100mA or less). Apply a Voltage of DC 500 V for 1 minute, according to the below method. (1) Between terminals. (2) Between terminal and Body. 输入 500V DC 电压 1 分钟,按如下接触方法测试: (1)端子与端子之间. (2)端子与外壳之间.		100mΩ Max 100mΩ以下
6.2			100MΩ Min 100 兆欧以上
6.3	Apply a Voltage of AC100 V (50~60Hz) for 1 minute, according to the below method. (1) Between terminals. (2) Between terminal and Body. 输入 100V AC 电压 1 分钟,按如下接触方法测试: (1) 端子与端子之间. (2) 端子与外壳之间.		No evidence of breakdown 无瞬断、击穿等破坏.
6.4	Bouncing 触点抖动	Operation speed: 3~4 times/s 操作速度: 每秒 3~4 次 Oscillo scope 示波器 Switch Bouncing Test Circuit 抖动测定回路.	Before Life cycle: On:5ms MAX,5 毫秒以下 Off: 5ms MAX,5 毫秒以下 After Life cycle: On:10ms MAX,10 毫秒以下 Off: 10ms MAX,10 毫秒以下



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7. Mechanical Performance/机械性能

Item 项 目	Description 项目描述	ormance/机械性能 Test Condition 测试条件	Requirement 规格要求
7.1	Place the vertical direction of switch operation and gradually increase the load applied to the center of the stem until it stop. 开关的动作方向为垂直放置,向手柄中心逐渐施加负荷直到停止. Place the vertical direction of switch operation and gradually increase the load applied to the center of the stem until it stop. Place the vertical direction of switch operation and gradually increase the load applied to the center of the stem until it stop. 开关的动作方向为垂直放置,向手柄中心逐渐施加负荷直到停止. 7.2		See page 11 见第 11 页
7.2			See page 11 见第 11 页
7.3			No damage (Electrical) And mechanical) 电气和机械性能正常.



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		F • • • • • • • • • • • • • • • • • • •					
7.4	Stem Pull Strength 手柄拉拔强 度	Break by a pull force app direction of stem operation 在推柄动作方向反向垂直 程度.	on.		5kgf	Min	
7.5	Shock 机械冲击	Measured by accordic condition: (1) Acceleration: 80g 为 (2) Cycles of test:3 cycle directions, for a total 试验次数: 每个方向:	加速度 es each in 6 of 18 cycles.	18 次.	Shall mee 7.2. 满足 6,7		
7.6	Life Test 寿命测试	1) D.C.12V 10mA resista D.C 12V 10mA 电图 2) Operation speed: 5-6 动作速度: 5-6 次/ 3) Push force: 150gf 按力: 150gf 5) Push travel: 3.5mm 按压行程: 3.5mm 6) Operation number: 动作次数: 50,000	且负荷 times / s 秒 50,000,000cycles	S	Contact re 1000 m Ω 接触电阻: Bouncing: 触点抖动: Operation Variation r. 30% 操作力的多 值的±30%	Max 1000 毫欧 10ms M 10 毫秒以 force: ate within 变化范围在	ax 以下 土

8. Environmental Performance/环境性能

Item Desc	ription Tost (Condition 测试条件	Requirement 规格要求
项目 项目	描述	CONDITION 测	Requirement



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8.1	Cold test 耐寒性	(1) Temperature: - 20±2℃ 温度: - 20±2℃ (2) Duration of test: 48h 持续时间: 48 小时 (3) Take off a drop water 去掉水珠 (4) Standard conditions after test: 1h 试验后的放置条件: 1 小时	Contact resistance: 200m Ω Max Shall meet: No. 6.2 to 6.4 No. 7.1 to 7.2 接触电阻 200m Ω 以下 满足: No. 6.2 to 6.4 No. 7.1 to 7.2
8.2	Heat test 耐热性	 (1) Temperature: 70±2℃ 温度: 70±2℃ (2) Duration of test: 48h 持续时间: 48 小时 (3) Take off a drop water 去掉水珠 (4) Standard conditions after test: 1h 试验后的放置条件: 1 小时 	Contact resistance: 200m Ω Max Shall meet: No. 6.2 to 6.4 No. 7.1 to 7.2 接触电阻 200m Ω以下 满足: No. 6.2 to 6.4 No. 7.1 to 7.2
8.3	Temperature cycle 温度循环	(1) Test cycles: 5 cycles 试验周期: 5 个周期 (2) Standard condition after test:1h 试验后的放置条件: 1 小时 Temperature 温度 Duration of te 持续时间 1 cycle 20±5℃ 1h -20±2℃ 1h 20±5℃ 1h 70±5℃ 1h	Contact resistance: 200m Ω Max Shall meet: No. 6.2 to 6.4 No. 7.1 to 7.2 接触电阻 200m Ω 以下 满足: No. 6.2 to 6.4 No. 7.1 to 7.2
8.4	Soldering heat test 耐焊接热	Soldering area: T/2 of PWB thickness. (PWB: T=1.6mm) 焊接面积: 印刷基板的 1/2 厚度处 Soldering temperature: 260±5℃ Soldering time: 5±0.5s 焊接温度: 260±5℃ 焊接时间: 5±0.5 秒	Appearance: No abnormality. 外观无异常



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8.5	Solder ability 可焊性	1. Hand soldering 手工焊接: Please practice according to below condition: (1) Soldering Temperature: 350±5℃ 焊接温度: 350±5℃ (2) Continual soldering time: 3±0.5s 连续焊接时间: 3±0.5秒 (1) Capacity of soldering iron: ≤20w 电烙铁功率: 20 瓦以下 2. Automatic PIP soldering 自动插板焊接: For the product of T/H according to below condition:	At least 95% of surface area of immersed portion shall be covered by solder. 侵焊面积大于 95%以上.
8.6	Humidity test 耐湿性	 (1) Temperature: 60±2℃ 温度: 60±2℃ (2) relative humidity: 90~95% R.H. 相对湿度:90~95% R.H. (3) Duration of test: 48h 持续时间: 48 小时 (4) Take off a drop water 去掉水珠 (5) Standard conditions after test: 1h 试验后的放置条件: 1 小时 	Contact resistance: 200m Ω Max Shall meet: No. 6.2 to 6.4 No. 7.1 to 7.2 接触电阻 200m Ω以下 满足: No. 6.2 to 6.4 No. 7.1 to 7.2
8.7	Salt Spray 盐雾测试	Apply the following environment to test: 根据下列条件进行测试: (1) Temperature: 35±5℃ 温度: 35±5℃; (2) Salt water density: 5±1% 盐水浓度: 5±1%; (3) Duration: 12hours 持续时间: 12 小时; (4) After test, the salt deposit shall be removed by running water. 实验后将盐沉积物用水冲掉	Appearance: No corrosion spot, no crack, no base plate naked. 外观: 无腐蚀点, 无裂纹, 无裸露基材. Contact Resistance: 200 m Ω Max 接触电阻: 200 毫欧以下



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		Apply the following e 根据下列条件进行测	st:	Appearar No corros crack, no	sion spot,	
		(1) Temperature: 35: (2) K ₂ S Density: 2%:	5℃	naked. 外观: 无原	•	
	Withstand	硫化钾浓度: 2%		无裸露基		农汉,
8.8	K ₂ S 硫化测试	(3) Duration: 2 minut 持续时间: 2 分钟				
				Contact F	Resistance	e:
				1000 m Ω	Max	
				接触电阻	:1000 毫	医欧以
				下		



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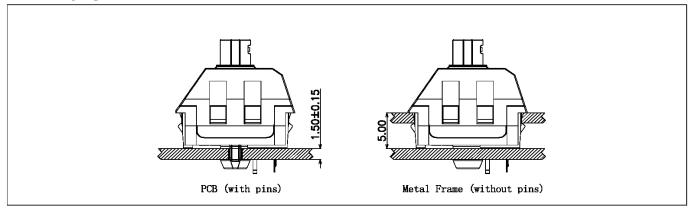
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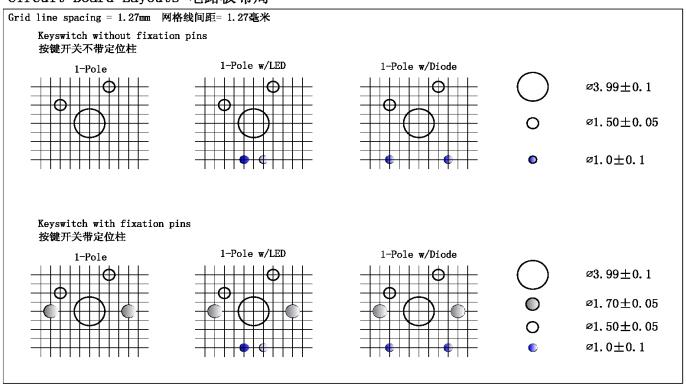
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9. Recommended PCB Layout 推荐的 PCB 安装焊盘规格

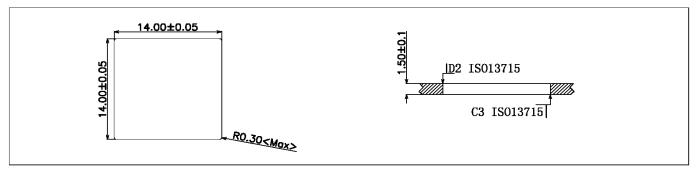
Mounting Options 安装选项



Circuit Board Layouts 电路板布局



Metal Frame Cutout Dimensions





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10. Loading Parameter (FP/OP/PT/OT /MD/CF/OF) Specification 荷重参数规格:

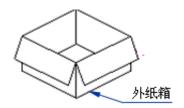
Parameter	Unit	Specification	Remark
FP(自由行程)	mm	15.25±0.2	
OP(动作位置)	mm	14.05 ± 0.7	
PT(导通行程)	mm	1.20±0.50	
OF(操作力)	gf	70±20	
TF(触感力)	gf	95±20	
OT(过行程)	mm	1.8	Min
MD(差动行程)	mm	0.6	Max
TT (全行程)	mm	3.5±0.50	

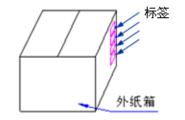
11. Packaging 包装

(1). Packaging type: Tray, 1000Pcs/Tray, 4000Pcs/Carton.

包装方式: Tray 盘,1000Pcs/盘,4000Pcs/箱.









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12.Precaution 注意事项

12.1 Immersion Soldering condition 浸焊条件

12.1 Infinite soil Soldering Condition 及片本丁	
ITEM	CONDITION
项目	条件
Preheat temperature	110℃ Max (Ambient temperature of soldering surface of P.W.B)
预热温度	110℃以下(印刷基板焊锡面周围的温度)
Preheat time 预热时间	60s, Max 60 秒以内
Area of flux	1/2 Max of PWB Thickness
助焊剂面积	印刷基板厚度的 1/2 以内
Temperature of solder	260±5℃
焊锡温度	260±5℃
Time of immersion	Within 5s
浸焊时间	5秒以内
Number of soldering	2time Max (But should down heat of the first soldering)
焊接次数	2次以内
Printed wiring board	Single side copper-clad laminates
印刷基板	单面铜箔

- (1) After switches were soldered, please be careful not to clean switches with solvent 开关浸焊后,注意不要用溶剂清洗.
- (2) Under the condition of using soldering iron, soldering temperature shall be 350℃ max within 3 sec. 在使用铬铁的情况下,焊锡温度应在350℃以下,焊接时间3秒以内.

12.2 Notes 注意点

- (1) Please be cautious not to give excessive static load or shock to switches.
 - 注意不要施加超负荷的压力或晃动开关.
 - (2) Please be careful not to stack up P. W. B. after switches were soldered. 开关焊接以后,印刷基板注意不要叠放.
 - (3) Preservation under high temperature and high humidity or corrosive gas should be avoided Especially. When you need to preserve for a long period, do not open the carton. 保管时尤其应注意避开高湿高温和有腐蚀性气体的环境.如需长时间保存,请不要打开包装箱.
 - (4) Products meet the ROHS & REACH environmental management substances control standards 产品满足 ROHS & REACH 环境管理物质管制标准